



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

**For: PROCESS AND INTEGRATION
SCHEME FOR FABRICATING
CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND
SEMICONDUCTOR COMPONENTS
INCLUDING CONDUCTIVE THROUGH-
WAFER VIAS**

Confirmation No.: 2525

Examiner: Ha T. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 2269-5859US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 9, 2004
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

SUPPLEMENTAL PRELIMINARY AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please revise the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 14 of this paper.

09/15/2004 JADD01 00000008 10668914

01 FC:1201 430.00 OP
02 FC:1202 432.00 OP